

**Amendments to the Specification:**

Please amend the specification as follows:

Please replace paragraph [0048] of the originally-filed specification with the following amended paragraph:

FIG. 5 is a flow diagram illustrating some of the steps for a process for creating capacitor 50. As shown in FIG. 5, a tantalum powder is pressed into tantalum encasement shells 55,56 to define a pair of anode slugs 51,52 (71). In some cases, the press used to create anodes 51,52 creates a series of tunnels or holes 54 in the anodes in order to aid in heat dissipation during the forming process and reduce ESR during operation. Optionally, one or more structural enhancing materials may be dispersed throughout the metallic powder prior to pressing the anode. Such materials are known as binders or binding agents and they are used primarily to provide increased structural integrity and to provide a changing density "gradient" to interior portions of anodes 51,52 during pressing. Such material can be used to control expansion, shrinkage or shape deformation. Such materials are preferably completely removed after pressing (prior to, during or after sintering). Thus, a suitable binder can be susceptible of complete removal simply as a result of the high temperature, high pressure sintering processing. In addition to or in lieu of the foregoing suitable material can be susceptible of completely dissolving in a fluid bath. The anodes are sintered prior to forming the tantalum pentoxide film over surfaces 57, 58. A tantalum pentoxide film is then formed on anodes 51,52, e.g., over surfaces 57, 58 to define the anode dielectric for anodes 51,52 (72). Although a specific sintering step is not depicted in FIG. 5, the present invention does not depend on a particular mode of sintering and those of skill in the art will apply appropriate temperatures and pressures to suitably sinter an anode slug.